

| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|-------|------|--|---|------------------|---------|------------------|
| S3 | 3534 | 257/758.ccls. | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 01:22 |
| S6 | 2841 | 257/758.ccls. and @ad<"20030225" | US-PGPUB; USPAT; EPO; JPO | OR | ON | 2005/12/12 01:24 |
| S7 | 2325 | 257/758.ccls. and @ad<"20030225" | USPAT; EPO; JPO | OR | ON | 2005/12/12 01:24 |
| S11 | 1036 | (257/758 or 257/759).ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 01:26 |
| S8 | 1834 | 257/758.ccls. and @ad<"20030225" | USPAT | OR | ON | 2005/12/12 01:59 |
| S12 | 1145 | 257/758.ccls. and @ad<"20030225" not S11 | USPAT | OR | ON | 2005/12/12 02:00 |
| S10 | 1007 | 257/758.ccls. and @ad<"20030225" | US-PGPUB; EPO; JPO | OR | ON | 2005/12/12 02:20 |
| S13 | 756 | 257/758.ccls. and @ad<"20030225" not S11 | US-PGPUB; EPO; JPO | OR | ON | 2005/12/12 02:20 |
| S4 | 2841 | 257/758.ccls. and @ad<"20030225" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:27 |
| S5 | 940 | 257/758.ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:27 |
| S14 | 1960 | 257/773.ccls. and @ad<"20030225" | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:27 |

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|-----|-------|--|--|----|----|------------------|
| S15 | 606 | 257/773.ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:27 |
| S16 | 505 | 257/773.ccls. and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5) not S5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:30 |
| S17 | 41203 | semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and (pillar or post or dummy or stress\$4 or reinforc\$5) not S5 | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:31 |
| S18 | 572 | semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and ((pillar or post or dummy) with (stress\$4 or reinforc\$5)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:31 |
| S19 | 1103 | semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and ((pillar or post or dummy) same (stress\$4 or reinforc\$5)) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:31 |
| S20 | 1053 | semiconductor and (ILD or interlayer or MLM or multilayer\$4 or metallization or interconnect or multilevel) and @ad<"20030225" and ((pillar or post or dummy) not S5) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/12/12 02:33 |